

ES3AF THRU ES3JF

PINNING

Surface Mount Superfast Recovery Rectifier

Reverse Voltage – 50 to 600 V Forward Current – 3 A

FEATURES

- For surface mounted applications
- Low profile package
- Glass Passivated Chip Juntion
- Superfast reverse recovery time
- Lead free in comply with EU RoHS 2011/65/EU directives

MECHANICAL DATA

• Case: SMAF

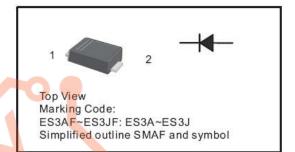
• Terminals: Solderable per MIL-STD-750, Method 2026

• pprox. Weight: 27mg 0.00086oz

Absolute Maximum Ratings and Characteristics

Ratings at 25°C ambient temperature unless otherwise specified. Single phase, half wave, 60 Hz, resistive or inductive load. For capacitive load, derate current by 20%.

55					
PIN	DESCRIPTION				
1	Cathode				
2	Anode				



Parameter	Symbols	ES3AF	ES3BF	ES3CF	ES3DF	ES3EF	ES3GF	ES3JF	Units
Maximum Repetitive Peak Reverse Voltage	V _{RRM}	50	100	150	200	300	400	600	٧
Maximum RMS voltage	V _{RMS}	35	70	105	140	210	280	420	٧
Maximum DC Blocking Voltage	V _{DC}	50	100	150	200	300	400	600	٧
Maximum Average Forward Rectified Current at T∟ = 100 °C	I _{F(AV)}		7		3				А
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load (JEDEC Method)	I _{FSM}	100							А
Maximum Forward Voltage at 3A	VF	1 1.25 1.				1.7	V		
Maximum DC Reverse Current Ta = 25 °C at Rated DC Blocking Voltage Ta = 125 °C	I _R				5 200				μА
Typical Junction Capacitance at V _R =4V, f=1MHz	Cj				45				pF
Maximum Reverse Recovery Time at I_F =0.5A, I_R =1A, I_{rr} =0.25A	t _{rr}				35				ns
Operating and Storage Temperature Range	Tj, Tstg	-55 ~ +150							°C

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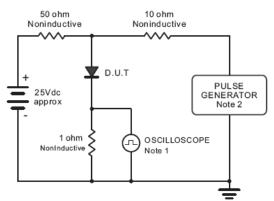
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Fig.1 Reverse Recovery Time Characteristic And Test Circuit Diagram



- Note: 1. Rise Time = 7ns, max. Input Impedance = 1megohm, 22pF.
 - 2. Ries Time =10ns, max. Source Impedance = 50 ohms.

+0.5

0

-0.25

10ns/div

Set time Base for 10ns/div

Fig.2 Maximum Average Forward Current Rating

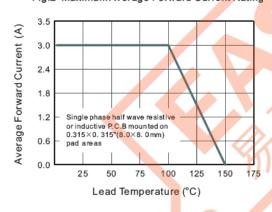


Fig.3 Typical Reverse Characteristics

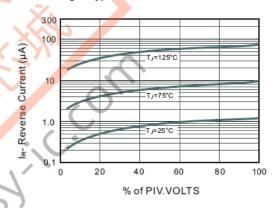


Fig.4 Typical Forward Characteristics

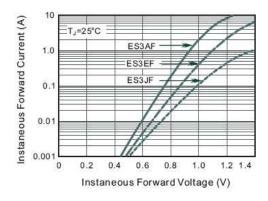
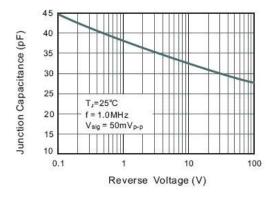


Fig.5 Typical Junction Capacitance



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REV.07

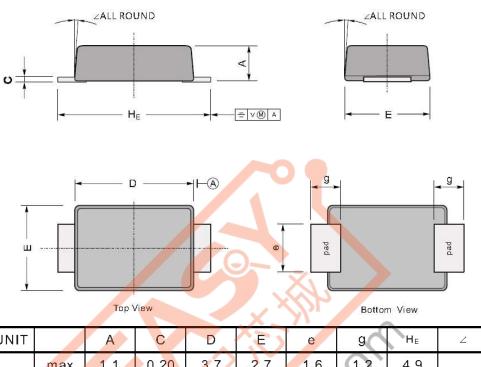


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PACKAGE OUTLINE

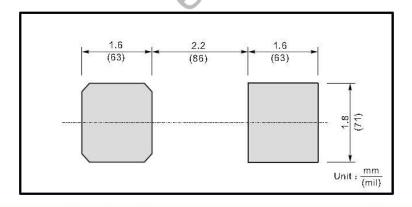
Plastic surface mounted package; 2 leads

SMAF



UNIT		Α	С	ם	(E)	е	9	H⊧	2
mm	max	1.1	0.20	3.7	2.7	1.6	1.2	4.9	
	min	0.9	0.12	3.3	2.4	1.3	0.8	4.4	7°
mil	max	43	7.9	146	106	63	47	193	<u>(</u>
	min	35	4.7	130	94	51	31	173	

The recommended mounting pad size



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